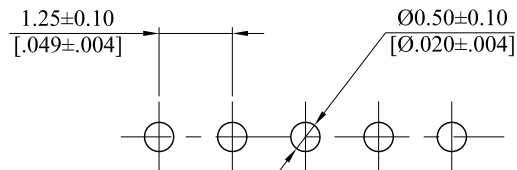
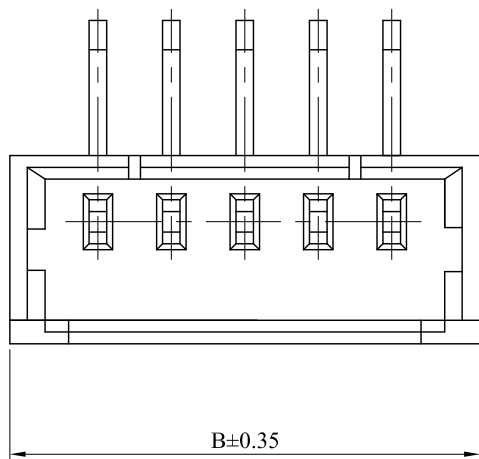


RoHS COMPLIANT

CUSTOMER DRAWING			
REV.	ECO. NO.	DESCRIPTION	DATE
B	ES090711	Upgrade drawing frame	2009.07.11
C	ES170924	Update the drawing	2017.08.18



Recommended PCB Layout

Note:
 Material:
 Insulator: High Temperature Thermoplastic, UL94 V-0, Natural
 Contact: Copper Alloy

General Part Number:

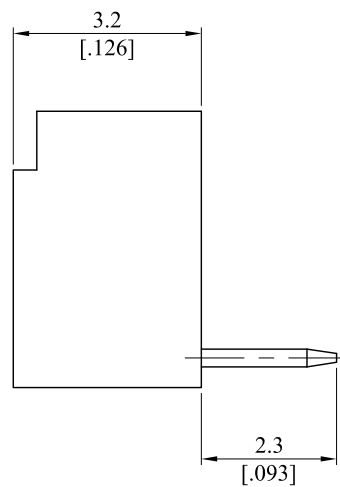
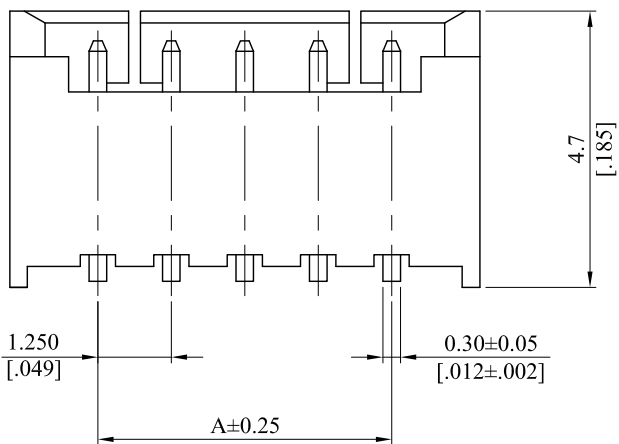
1254P ** H * 00
 1 2

1. No. of circuits(02~15)

2. Plating:

- 0=Matte Tin plated 80µ"min. over 30µ"min. Nickel underplating overall
- F=Selective Gold flash on contact area over 30µ"min. Nickel underplating overall, Tin plated on solder tails
- J= 15µ"min. Selective Gold on contact area over 30µ"min. Nickel underplating overall, Tin plated on solder tails
- K=30µ"min. Selective Gold on contact area over 30µ"min. Nickel underplating overall, Tin plated on solder tails

A=1.25mm(.049")*No. of spaces
 B=A+6.00mm(.236")
 C=A+3.00mm(.118")



TOLERANCE UNLESS OTHERWISE SPECIFIED			LEOCO CORPORATION http://www.leoco.com.tw		
mm	mm	inch	APPROVED BY:	DATE:	TITLE:
[inch]			Chard	2017.08.18	1.25mm(.049") Pitch Wafer
			Checked BY:	DATE:	
1 PLACE	± 0.30	± ---	Angel	2017.08.18	PART NO.: 1254P**H*00
2 PLACES	± 0.20	± .012	Brian	2017.08.18	
3 PLACES	± 0.10	± .008			
4 PLACES	± ---	± .004			
ANGULAR ±1°			SIZE:	SCALE:	DRAWING NO.:
			A3	1:1	125408S
			REV.:		SHEET:
			C		1 OF 1